

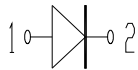
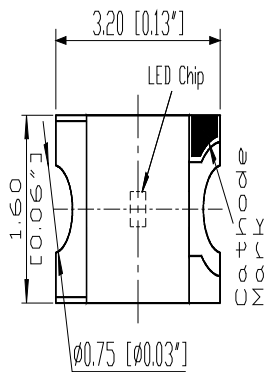
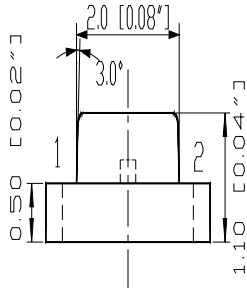
SURFACE MOUNT LED LAMPS

表面黏著型發光二極體指示燈

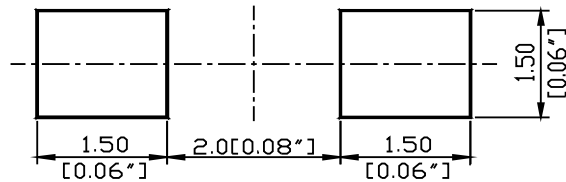
S150 Series SMD Chip LED Lamps

Part Number: S150G8S4

Package outlines



RECOMMEND PAD LAYOUT



ITEM	MATERIALS
Resin (mold)	Epoxy
Bonding wire	□ 25 μm Au
Lens color	Water transparent
Printed circuit	BT (White)
Dice	InGaN
Emitted color	Green



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
SENSITIVE DEVICES

NOTES:

1. All dimensions are in millimeters (inches);
2. Tolerances are ±0.1mm (0.004inch) unless otherwise noted.

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Part Number: S150G8S4

Absolute maximum ratings (T_A=25°C)

Parameter	Symbol	Value	Unit
Forward current	I _f	30	mA
Reverse voltage	V _r	5	V
Power dissipation	P _d	114	mW
Operating temperature range	T _{op}	-20 ~+80	°C
Storage temperature range	T _{stg}	-20 ~+80	°C
Peak pulsing current (1/8 duty f=1kHz)	I _{fp}	125	mA

Electro-optical characteristics (T_A=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
Wavelength at peak emission	I _f =20mA	λ _{peak}	--	525	--	nm
Spectral half bandwidth	I _f =20mA	Δλ	--	25	--	nm
Dominant wavelength	I _f =20mA	λ _{dom}	525	530	535	nm
Forward voltage	I _f =20mA	V _f	--	3.3	3.8	V
Luminous intensity *1	I _f =20mA	I _v		600	--	mcd
Viewing angle at 50% I _v	I _f =10mA	2θ _{1/2}	--	140	--	Deg
Reverse current	V _r =5V	I _r	--	--	10	μA

*1 Note: Luminous intensity tolerance is ±10% .

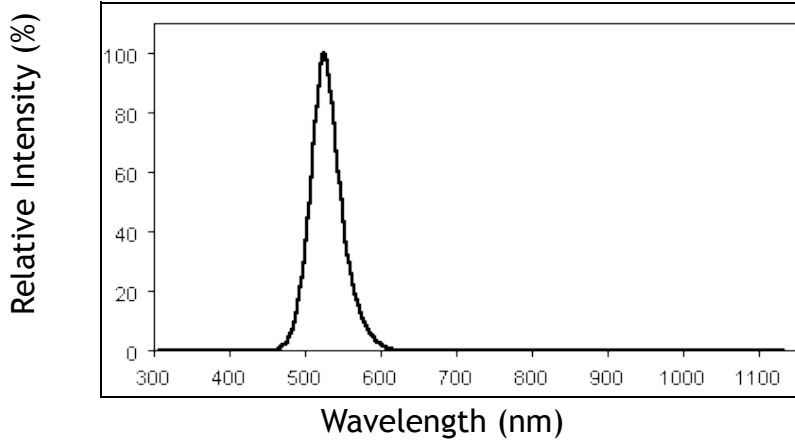
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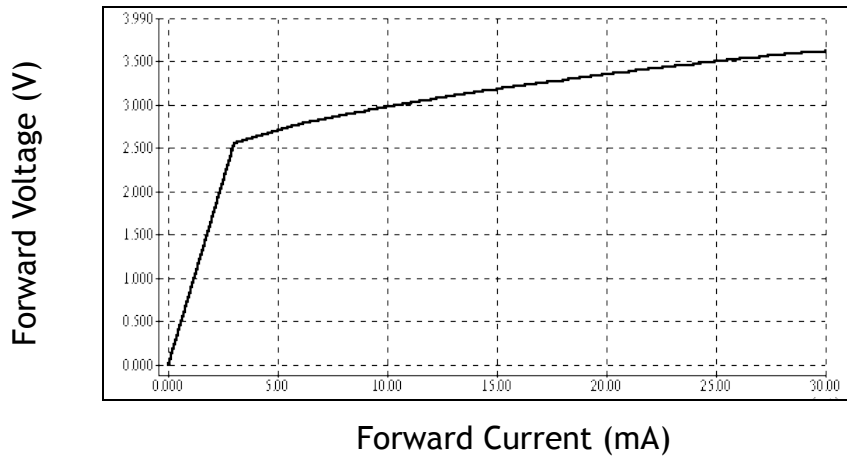
Part Number: S150G8S4

OPTICAL CHARACTERISTIC CURVES

Relative Intensity vs. Wavelength

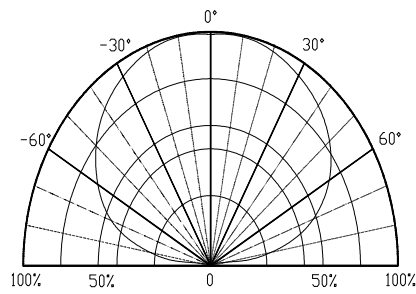


Forward Current vs. Forward Voltage



Forward Current (mA)

Directive Characteristics

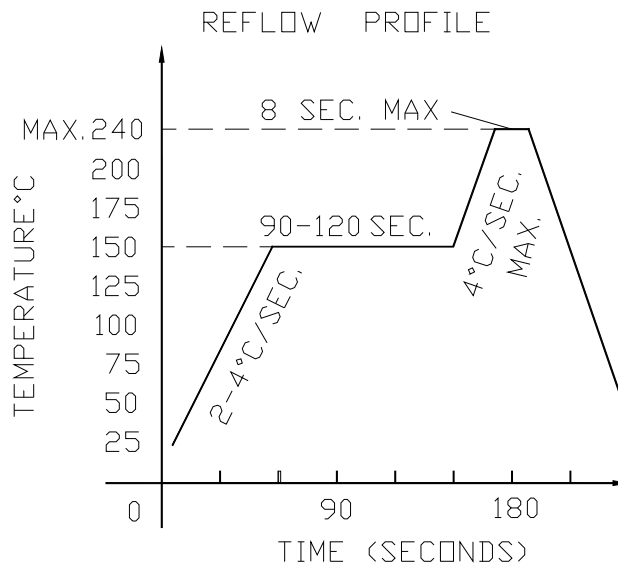


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Reflow Profile

■ Reflow Temp/Time



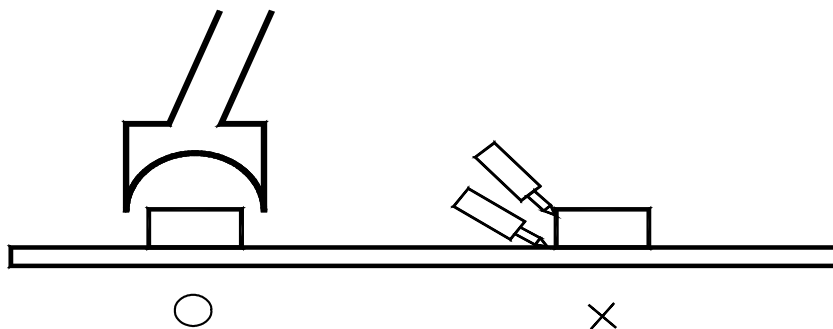
■ Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter

($+10^\circ\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device

■ Rework

1. Customer must finish rework within 5 sec under 260°C .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.

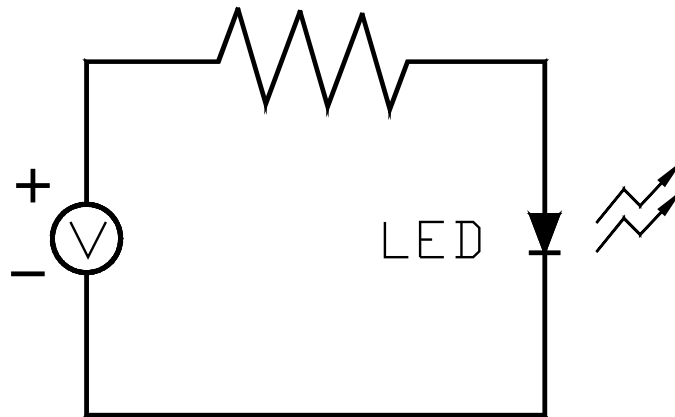


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Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause

big current change (Burn out will happen).

2.Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : $5^{\circ}\text{C}\sim 30^{\circ}\text{C}$ ($41^{\circ}\text{F}\sim 86^{\circ}\text{F}$)

2.2 Shelf life in sealed bag: 12 month at $< 5^{\circ}\text{C}\sim 30^{\circ}\text{C}$ and $< 30\%$ R.H. after the package is

Opened, the products should be used within a week or they should be keeping to stored at

≤ 20 R.H. with zip-lock sealed.

3.Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The

Conditions are as followings:

3.1 $60\pm 3^{\circ}\text{C}$ x(12~24hrs) and $< 5\%$ RH, taped reel type

3.2 $100\pm 3^{\circ}\text{C}$ x(45min~1hr), bulk type

3.3 $130\pm 3^{\circ}\text{C}$ x(15~30min), bulk type

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Test items and results of reliability

Type	Test Item	Test Conditions	Note	Number of Damaged
Requirement	Temperature Cycle	-20°C 30min ↑↓ 80°C 30min	100 cycle	0/22
	Thermal Shock	-20°C 15min ↑↓ 80°C 15min	100 cycle	0/22
	High Humidity Heat Cycle	30°C ↔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22
	High Temperature Storage	T _a =80°C	1000 hrs	0/22
	Humidity Heat Storage	T _a =60°C RH=90%	1000 hrs	0/22
	Low Temperature Storage	T _a =-30°C	1000 hrs	0/22
Seperation	Life Test	T _a =25°C I _F =20mA	1000 hrs	0/22
	High Humidity Heat Life Test	60°C RH=90% I _F =20mA	500 hrs	0/22
	Low Temperature Life Test	T _a =-20°C I _F =20mA	1000 hrs	0/22